

PCN Number:	20160630001	PCN Date:	Dec 13, 2016
Title:	DFAB VLCT Offload to SCT		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	June 13, 2017		
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the transfer of select high volume demand devices using VLCT tester in DFAB (Dallas South bldg. North Campus) to VLCT tester EBT/SCT (Dallas SC Building in North Campus).

Test programs are identical.

Test hardware configurations identical.

Reason for Change:

- Consolidate the VLCT tester to one probe facility
- Mitigate test capacity shortage in DFAB.
- Material test cycle time improvement.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Site	site code (20L)	country code (21L)
DFAB	DFB	USA

New

Site	site code (20L)	country code (21L)
SCT	DM4	USA

Example shipping label (not actual product label)

 <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:</p>			<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS</p>
<p>MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04</p>		<p>OPT: 39 ITEM: LBL: 5A (L)T0:1750</p>	

Product Affected:

SN0605104PJ-A	TPIC44L01DBG4	TPIC46L02DBG4	TPIC6C595DR
SN104217NSR-A	TPIC44L01DBR	TPIC46L02DBR	TPIC6C595DRG4
SN104479DWR	TPIC44L02DB	TPIC46L02DBRG4	TPIC6C595N
SN65HVD1040QDRQ1	TPIC44L02DBG4	TPIC6B595DW	TPIC6C595PW
SN65HVD1050AQDRQ1	TPIC44L02DBR	TPIC6B595DWG4	TPIC6C595PWG4
SN65HVD1050QDRQ1	TPIC44L02DBRG4	TPIC6B595DWR	TPIC6C595PWR
SN65HVDA1050AQDR-M	TPIC46L01DB	TPIC6B595DWRG4	TPIC6C595PWRG4
SN65HVDA1050AQDRQ1	TPIC46L01DBG4	TPIC6B595N	TPIC74100QPWPRQ1
TLC5941QPWPRQ1	TPIC46L01DBR	TPIC6C595D	TPIC74100QPWPRLRD
TPA6211A1TDGNRQ1	TPIC46L01DBRG4	TPIC6C595DG4	TPIC74101QPWPRQ1
TPA6211A1TDNVRQ1	TPIC46L02DB		TUSB1106IPWRQ1
TPIC44L01DB			

DFAB/SCT VLCT offload Correlation Report

Sedta Boorananut

06/15/16

BPR146L01CZ8

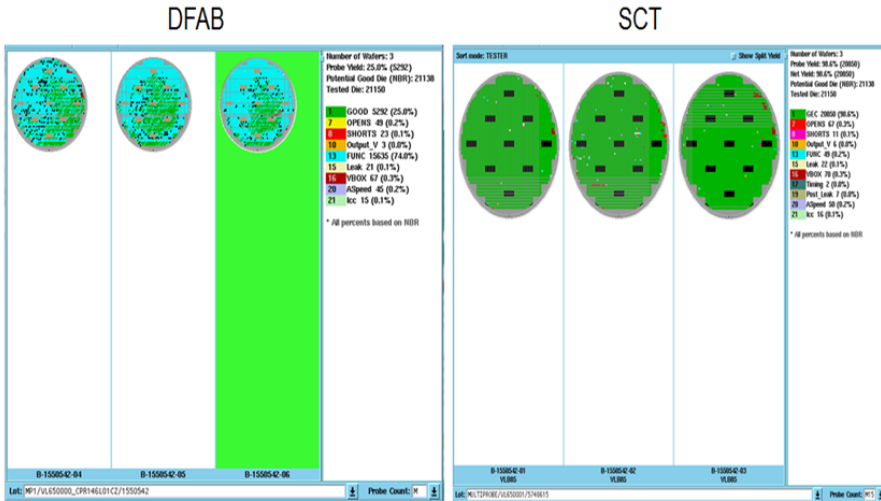
BLBFIC74100DZ8

BLBF1050ABZ8

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SCT/DFAB Correlation Data– BPR146L01CZ8 offload to SCT



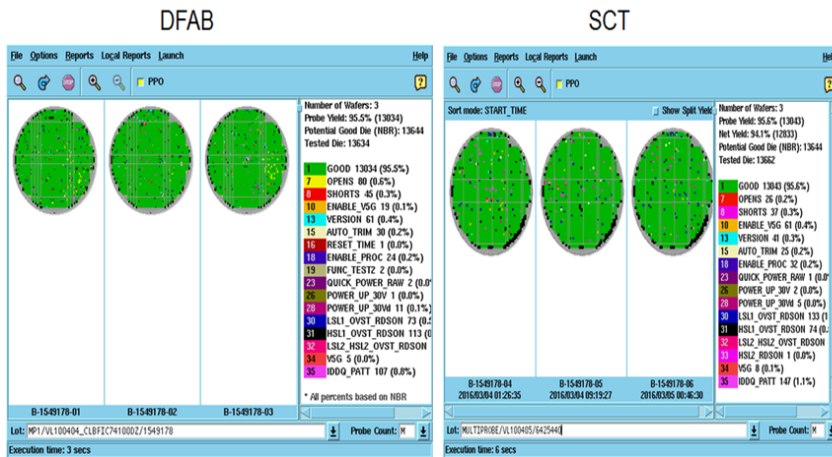
VL650001_TJ3
Parametric Quad Analysis

Cpk >= 1.67	Q1: 211 of 253	Q2:
Cpk < 1.67(*)	Q3: 24 of 253	Q4:
	< 1.5 Sigma Shift	>= 1.5

- (*) or Cpk < 0.5 X Base Cpk
- Unclassified tests: 7
- Click in a quad to view plots of the tests

- DFAB Yield 25% compared to SCT Yield 98.6%
- SCT has zero GEC due to bin13 on the VL650000 program (original program).
- SCT have to work on the VL650001 program to address bin13 issue and address the SCT automation issue (Change Temp type from Temp_25C_Deg to Temp_30C_Deg and add Pin List for Auto-Z routine).
- See the Parametric quad analysis on the follow link <http://home.dal.design.ti.com/~a0864045/1550542>

SCT/DFAB Correlation Data– BLBFIC74100DZ offload to SCT



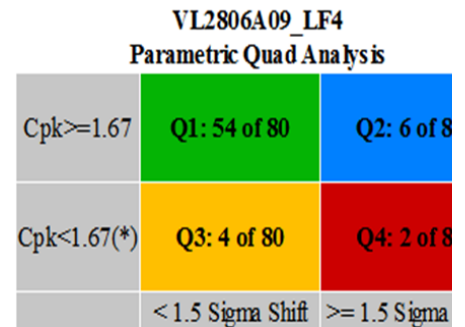
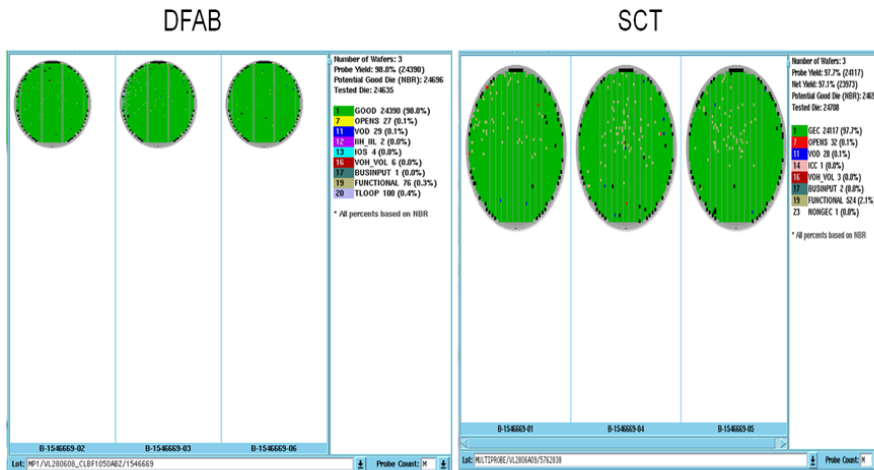
VL100405_FT3 Parametric Quad Analysis

Cpk >= 1.67	Q1: 96 of 143	Q2: 2 of 143
Cpk < 1.67 (*)	Q3: 43 of 143	Q4: 1 of 143
	< 1.5 Sigma Shift	>= 1.5 Sigma Shift

- (*) or Cpk < 0.5 X Base Cpk
- Unclassified tests: 1
- Click in a quad to view plots of the tests.

- DFAB Yield 95.5% compared to SCT Yield 95.6%
- SCT have to modify test program on the VL100405 program to address the SCT automation issue (Change Temp type from Temp_25C_Deg to Temp_30C_Deg and add Pin List for Auto-Z routine.
- See the Parametric quad analysis on the follow link <http://home.dal.design.ti.com/~a0864045/1549178>
- Most of the parameters shows the low Cpk and relate to the bin13.

SCT/DFAB Correlation Data– BLBF1050ABZ offload to SCT



- (*) or Cpk < 0.5 X Base Cpk
- Unclassified tests: 14
- Click in a quad to view plots of the tests.

- DFAB Yield 98.8% compared to SCT Yield 97.7%
- SCT have to modify test program on the VL280609 program to address the SCT automation issue (Change Temp type from Temp_25C_Deg to Temp_30C_Deg and add Pin List for Auto-Z routine).
- See the Parametric quad analysis on the follow link <http://home.dal.design.ti.com/~a0864045/1546669/>

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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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